

Patent Abstracts of Japan

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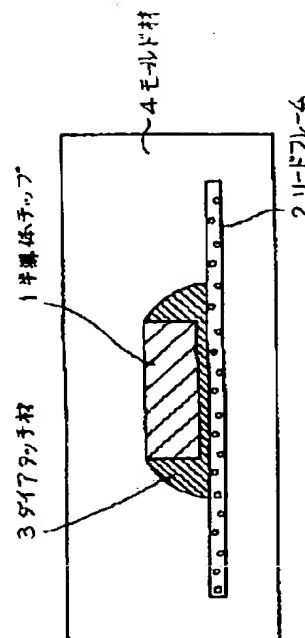
APPLICATION DATE : 21-08-90
APPLICATION NUMBER : 02219788

APPLICANT : SEIKO INSTR INC;

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TITLE : MOUNTING OF SEMICONDUCTOR
DEVICE



ABSTRACT : PURPOSE: To reduce stress from a mold material on the end of a semiconductor chip by controlling the amount of die-attach material so that the side of said semiconductor chip may be covered.

CONSTITUTION: A semiconductor chip 1 is fixedly installed to a lead frame 2 by way of a die-attach material 3. The amount of a die-attach material 3 is controlled so that the die-material may cover the side of the semiconductor chip 1. Then, the mold material is made to cover all the semiconductor chip 1 and the lead frame 2. This construction makes it possible to reduce stress induced from the mold material to the end of the semiconductor chip.

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